

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1027972	(insulat\$3 dielectric)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L2	920779	L1 and (via hole contact groove recess open\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L3	474726	L2 and temperature	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L4	95634	L3 and stress	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L5	25599	L4 and (thermal near5 expansion)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L6	395	L5 and (elastic near5 coefficient)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L7	20	L6 and (poisson near5 ratio)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:39
L8	1116334	(insulat\$3 dielectric)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 10:40
L9	393057	L8 and (via hole contact groove recess open\$3)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 10:40
L10	40214	L9 and temperature	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 10:40
L11	1222	L10 and (thermal and expansion)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 10:40
L12	1006	L11 and (thermal near5 expansion)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 10:40
L13	1222	L11 L12	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 10:40

L14	0	L13 and (elastic and coefficient)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:40
L15	0	L13 and (elastic and coefficient)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:40
L16	124679	(thermal near5 expansion)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:18
L17	44868	((thermal near5 expansion) same (via open\$3 hole trench contact recess groove))	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:19
L18	10757	17 and semiconductor	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:44
L19	10371	18 and (interconnect wir\$3 copper aluminum "Cu" "Al")	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:20
L20	7847	19 and (dielectric insulat\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 10:45
L21	4949	20 and (oxide nitride)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:20
L22	4380	21 and thickness	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:03
L23	3980	22 and temperature	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:19
L24	3521	23 and (elastic coefficient)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:07
L25	0	24 and ((poission poission\$2) near5 ratio)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:17
L26	1961	24 and (poission ratio)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:17
L27	2	24 and poission	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/12 11:17
L28	68173	(thermal near5 expansion)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 11:19

L29	19674	28 and (via open\$3 hole trench contact recess groove)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 11:19
L30	6188	29 and temperature	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 11:19
L31	1249	30 and (interconnect wir\$3 copper aluminum "Cu" "Al")	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 11:20
L32	153	31 and (oxide nitride)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/12 11:24